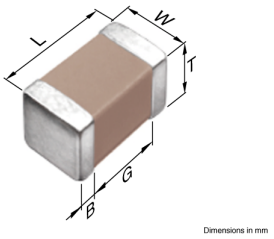
Creation Date : May 19, 2017 (GMT)

Multilayer Ceramic Chip Capacitors

C2012X7R0J475M085AB

RoHS | REACH SVHC-Free | Halogen Free | Lead Free

TDK item description	C2012X7R0J475MT****
Applications	Commercial Grade
Feature	General (Up to 50V)
Series	C2012 [EIA 0805]
Status	Production (Not Recommended for New Design)



Size	
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	0.85mm ±0.15mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	4.7µF ±20%
Rated Voltage	6.3VDC
Temperature Characteristic	X7R(±15%)
Dissipation Factor (Max.)	10%
Insulation Resistance (Min.)	21MΩ

Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

! Images are for reference only and show exemplary products.
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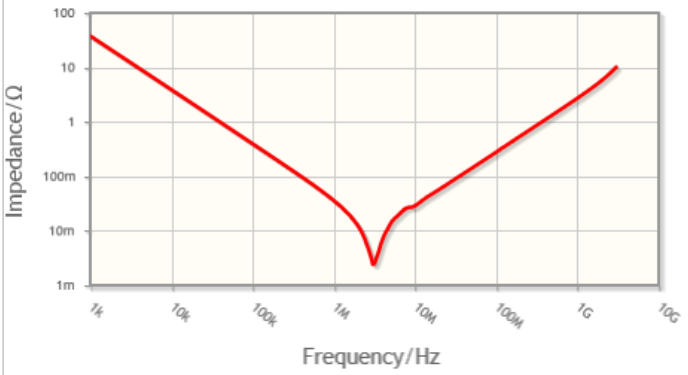
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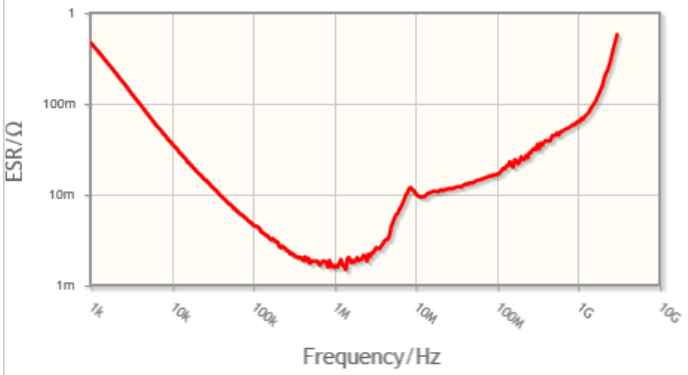
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

Impedance



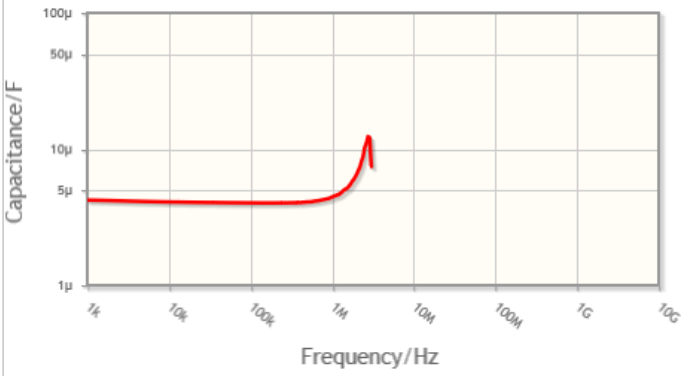
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ESR



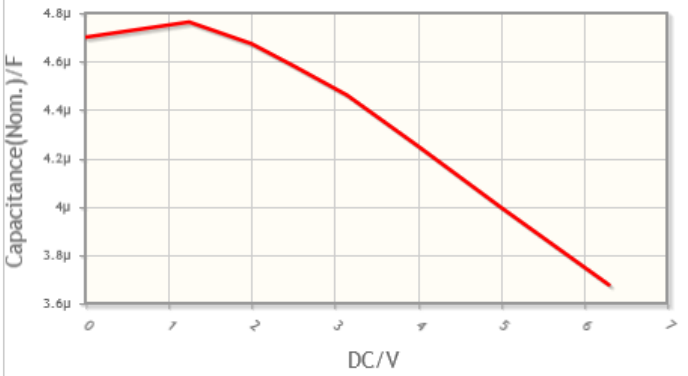
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Capacitance



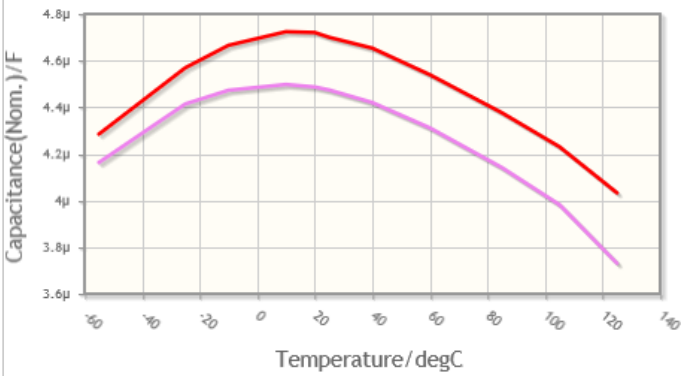
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DC Bias Characteristic



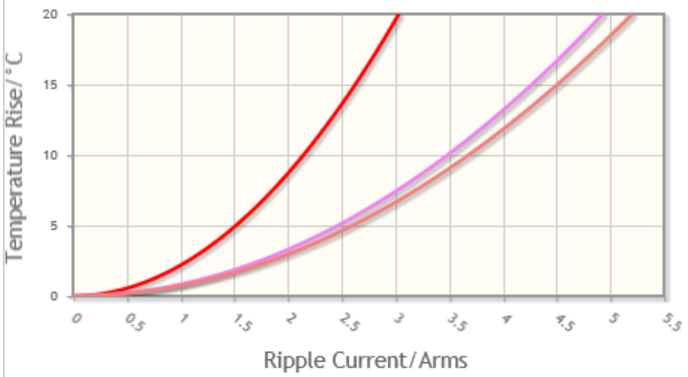
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Temperature Characteristic



C2012X7R0J475M085AB(No Bias) C2012X7R0J475M085AB(DC Bias = 3.15V)

Ripple Temperature Rising



C2012X7R0J475M085AB(100kHz) C2012X7R0J475M085AB(500kHz) C2012X7R0J475M085AB(1MHz)

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Associated Images

Land Pattern (Terminal Connection)



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